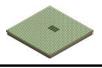
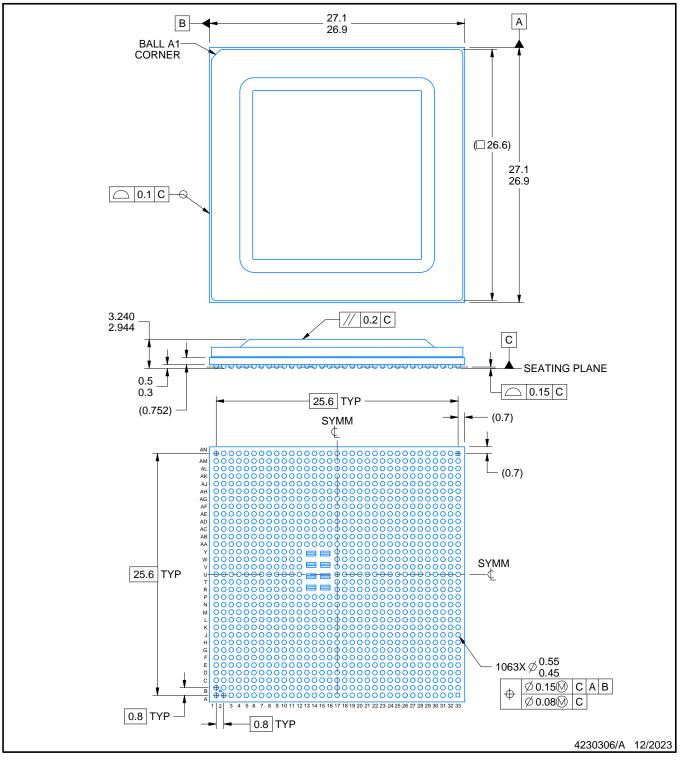
AND1063A



PACKAGE OUTLINE

FCBGA - 3.24 mm max height

BALL GRID ARRAY



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.2. This drawing is subject to change without notice.

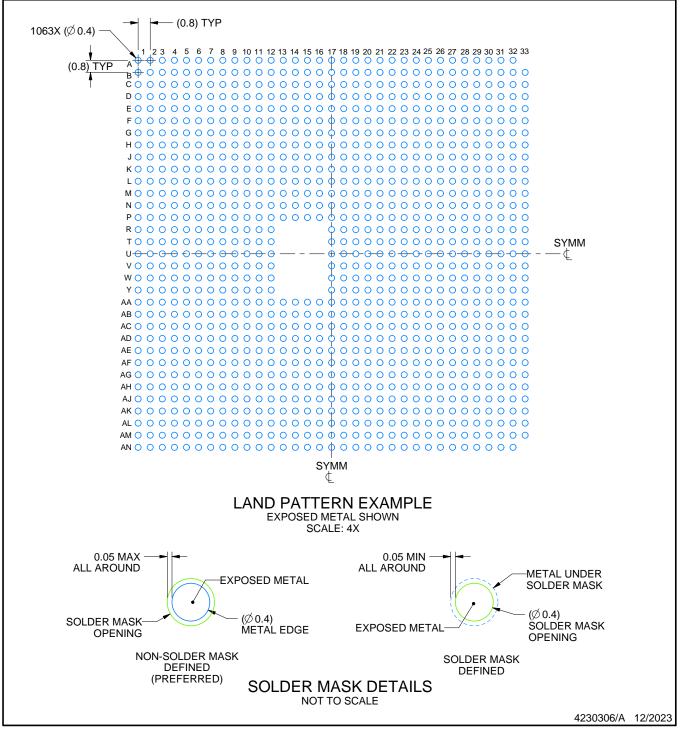


AND1063A

EXAMPLE BOARD LAYOUT

FCBGA - 3.24 mm max height

BALL GRID ARRAY



NOTES: (continued)

3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For information, see Texas Instruments literature number SPRAA99 (www.ti.com/lit/spraa99).

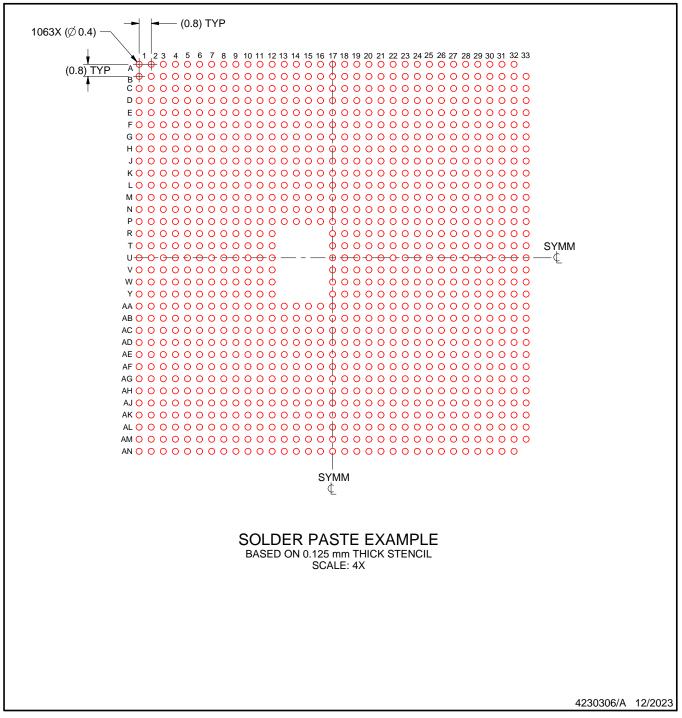


AND1063A

EXAMPLE STENCIL DESIGN

FCBGA - 3.24 mm max height

BALL GRID ARRAY



NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.



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